

L Number	Hits	Search Text	DB	Time stamp
1	16	((sendust or permalloy) same wafer) same clean\$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/08 15:40
2	2	(sendust same wafer) same clean\$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/08 15:40
3	56	sendust same wafer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/08 15:43
4	45	(sendust same wafer) and @pd<20011012	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/08 15:49
5	0	acid same ((metal near etch\$3) same (chromium near sulfate))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/08 15:50
6	0	((metal near etch\$3) same (chromium near sulfate))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/08 15:50
7	10	((metal same etch\$3) same (chromium near sulfate))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/08 16:03
8	157	(post near "CMP") same ((clean\$3 or remov\$3 or etch\$3) same particle)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/08 16:09
9	54	((post near "CMP") same ((clean\$3 or remov\$3 or etch\$3) same particle)) and @pd<20011012	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/08 16:10
10	22	((((post near "CMP") same ((clean\$3 or remov\$3 or etch\$3) same particle)) and @pd<20011012) and (metal same etch\$3))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/08 17:24
11	0	(((((post near "CMP") same ((clean\$3 or remov\$3 or etch\$3) same particle)) and @pd<20011012) and (metal same etch\$3)) and ((chromium or "Cr" or ferric or "Fe") near sulfate))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/08 17:24
12	2	(((((post near "CMP") same ((clean\$3 or remov\$3 or etch\$3) same particle)) and @pd<20011012) and (metal same etch\$3)) and 252/79.1.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/08 17:24
-	1	(polish\$3 same (super near finish\$3)) same slurry	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/08 12:24

-	0	(((polish\$3 same (super near finish\$3)) same slurry) and (acid or base or alkali)) and abrasive ) and ("pH")	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/06 14:53
-	1	(((polish\$3 same (super near finish\$3)) same slurry) and (acid or base or alkali)) and abrasive	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/06 14:53
-	1	((polish\$3 same (super near finish\$3)) same slurry) and (acid or base or alkali)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/06 14:55
-	2335	(polish\$3 same slurry) same (acid or base or alkali)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/06 14:56
-	740	((polish\$3 same slurry) same (acid or base or alkali)) same ("pH")	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/06 14:57
-	70	(((polish\$3 same slurry) same (acid or base or alkali)) same ("pH")) same etch\$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/06 14:58
-	28	(((polish\$3 same slurry) same (acid or base or alkali)) same ("pH")) same etch\$3 ) and @pd<20011012	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/06 14:59
-	5	((((polish\$3 same slurry) same (acid or base or alkali)) same ("pH")) same etch\$3 ) and @pd<20011012) and (metal near etch\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/06 14:59
-	4	("6402851").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/06 15:50
-	0	"6236542".pn. and (sendust or permalloy)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/06 15:51
-	1	((sendust or permalloy) near5 wafer) same ((remov\$3 or clean\$3) same (slurry near particle))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/06 15:56
-	2036	((remov\$3 or clean\$3) same (slurry near particle))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/06 15:55
-	509	(( ((remov\$3 or clean\$3) same (slurry near particle)))) same wafer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/06 15:55

-	1	(( ((remov\$3 or clean\$3) same (slurry near particle))) same wafer) and ((sendust or permalloy) near5 wafer)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/06 15:57
-	1	(( ((remov\$3 or clean\$3) same (slurry near particle))) same wafer) and ((sendust or permalloy) same wafer)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/06 15:57
-	1	(( ((remov\$3 or clean\$3) same (slurry near particle))) same wafer) and (sendust or permalloy)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/06 15:58
-	438	(sendust or permalloy) same wafer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/06 15:59
-	1	( (sendust or permalloy) same wafer) same ("NIP")	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/08 14:20
-	9	( (sendust or permalloy) same wafer) same (disk near5 magnetic)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/06 16:01
-	2077	(clean\$3 or etch\$3 or remov\$3) same ( slurry near particle)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/08 12:27
-	134	((clean\$3 or etch\$3 or remov\$3) same ( slurry near particle)) and 134/\$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/08 12:26
-	70	((((clean\$3 or etch\$3 or remov\$3) same ( slurry near particle)) and 134/\$.ccls.) and @pd<20011012	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/08 12:30
-	66	((clean\$3 or etch\$3 or remov\$3) same ( slurry near particle)) same (acid and chromium near sulfate or "Cr" or iron or "Fe")	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/08 12:29
-	44	((((clean\$3 or etch\$3 or remov\$3) same ( slurry near particle)) same (acid and chromium near sulfate or "Cr" or iron or "Fe") ) and @pd<20011012	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/03/08 12:30